



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS621L1 E3128A		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA001125092						
<b>Package</b>		PG-TO263-7-2		<b>Weight*</b>		1509.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.015	0.46	0.46	4647	4647
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		160	
	non noble metal	iron	7439-89-6	0.803	0.05		532	
	non noble metal	copper	7440-50-8	801.714	53.09	53.16	531122	531814
	non noble metal	aluminium	7429-90-5	3.189	0.21	0.21	2112	2112
wire	non noble metal	aluminium	7429-90-5	3.189	0.21	0.21	2112	2112
encapsulation	organic material	carbon black	1333-86-4	6.298	0.42		4172	
	inorganic material	antimonytrioxide	1309-64-4	13.168	0.87		8723	
	plastics	brominated resin	-	14.885	0.99		9861	
	plastics	epoxy resin	-	108.777	7.21		72064	
	inorganic material	silicondioxide	60676-86-0	429.384	28.45	37.94	284461	379281
leadfinish	non noble metal	tin	7440-31-5	12.317	0.82	0.82	8160	8160
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	178	179
solder	non noble metal	tin	7440-31-5	0.101	0.01		67	
	noble metal	silver	7440-22-4	0.127	0.01		84	
	non noble metal	lead	7439-92-1	4.834	0.32	0.34	3202	3353
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		70	
	non noble metal	copper	7440-50-8	106.210	7.04	7.05	70363	70454
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com